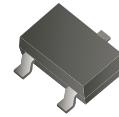


# CMS01P10TA-HF

P-Channel  
RoHS Device  
Halogen Free



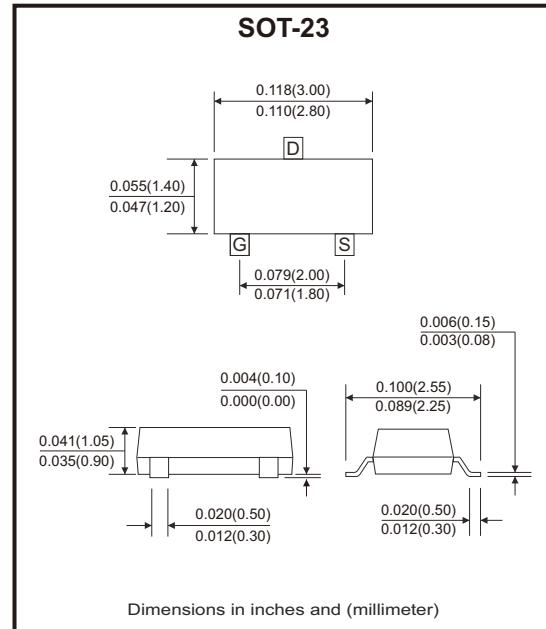
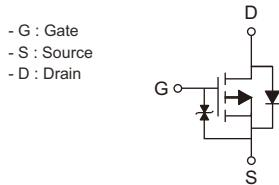
## Features

- Low on resistance.
- Low gate charge.
- Fast switching characteristic.
- ESD protected gate.

## Mechanical data

- Case: SOT-23, molded plastic.
- Mounting position: Any.

## Circuit Diagram



## Maximum Ratings (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain source voltage	$V_{DS}$	-100	V
Gate source voltage	$V_{GS}$	$\pm 20$	
Continuous drain current @ $V_{GS} = -10\text{V}$ , $T_A = 25^\circ\text{C}$ (Note 1)	$I_D$	-0.9	A
Continuous drain current @ $V_{GS} = -10\text{V}$ , $T_A = 70^\circ\text{C}$ (Note 1)	$I_D$	-0.7	
Pulsed drain current (Note 2)	$I_{DM}$	-3.6	
Continuous body diode forward current @ $T_A = 25^\circ\text{C}$ (Note 1)	$I_S$	-0.7	
ESD susceptibility (Note 3)	$V_{ESD}$	2000	V
Total power dissipation @ $T_A = 25^\circ\text{C}$ (Note 1)	$P_D$	0.9	W
Total power dissipation @ $T_A = 70^\circ\text{C}$ (Note 1)	$P_D$	0.6	
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150	°C
Thermal resistance, junction to ambient (Note 1)	$R_{\theta JA}$	145	°C/W

Notes: 1. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The power dissipation  $P_D$  is based on  $R_{\theta JA}$  and the maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design.

2. Repetitive rating, pulse width limited by junction temperature  $T_J(\text{MAX})=150^\circ\text{C}$ . Ratings are based on low frequency and low duty cycles to keep initial  $T_J=25^\circ\text{C}$ .

3. Human body model, 1.5kΩ in series with 100pF.

## Electrical Characteristics (at TA=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
Drain source breakdown voltage	V <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-100			V
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1		-2.5	
Forward transconductance	g <sub>fS</sub>	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1A		2.5		S
Gate body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±16V, V <sub>DS</sub> = 0V			±10	μA
Zero gate voltage drain current	I <sub>BSS</sub>	V <sub>DS</sub> = -80V, V <sub>GS</sub> = 0V			-1	
Static drain source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -1A		440	600	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -0.5A		520	730	
<b>Dynamic</b>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -50V, V <sub>GS</sub> = 0V, f = 1MHz		270		pF
Output capacitance	C <sub>oss</sub>			20		
Reverse transfer capacitance	C <sub>rss</sub>			21		
Gate resistance	R <sub>g</sub>	f = 1MHz		5.4		Ω
Total gate charge (Note 1,2)	Q <sub>g</sub>	V <sub>DS</sub> = -50V, I <sub>D</sub> = -1A, V <sub>GS</sub> = -10V		6.6		nC
Gate source charge (Note 1,2)	Q <sub>gs</sub>			1		
Gate drain charge (Note 1,2)	Q <sub>gd</sub>			1.5		
Turn-on delay time (Note 1,2)	t <sub>d(on)</sub>	V <sub>DS</sub> = -50V, I <sub>D</sub> = -1A, V <sub>GS</sub> = -10V, R <sub>GS</sub> = 6Ω		8.2		ns
Rise time (Note 1,2)	t <sub>r</sub>			1.2		
Turn-off delay time (Note 1,2)	t <sub>d(off)</sub>			21		
Fall time (Note 1,2)	t <sub>f</sub>			1.8		
<b>Source-Drain Diode</b>						
Diode forward voltage (Note 1)	V <sub>SD</sub>	I <sub>S</sub> = -1A, V <sub>GS</sub> = 0V		-0.82	-1.2	V
Body diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = -1A, dI <sub>F</sub> /dt = 100A/μs		17		ns
Body diode reverse recovery charge	Q <sub>rr</sub>			12		

Notes: 1. Pulse width ≤ 300μs, duty cycle ≤ 2%.

2. Independent of operating temperature.

## Rating and Characteristic Curves (CMS01P10TA-HF)

Fig.1 - Typical Output Characteristics

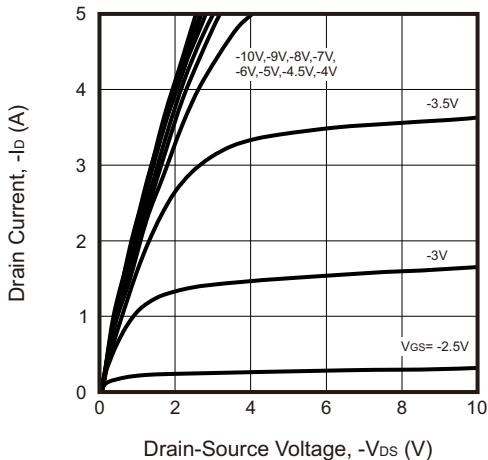


Fig.2 - Breakdown Voltage vs Ambient Temperature

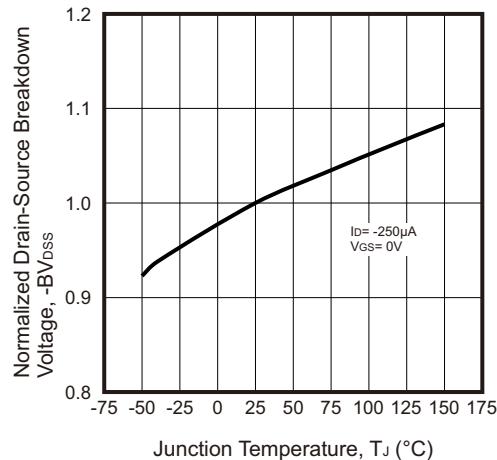


Fig.3 - Static Drain-Source On-State Resistance vs Drain Current

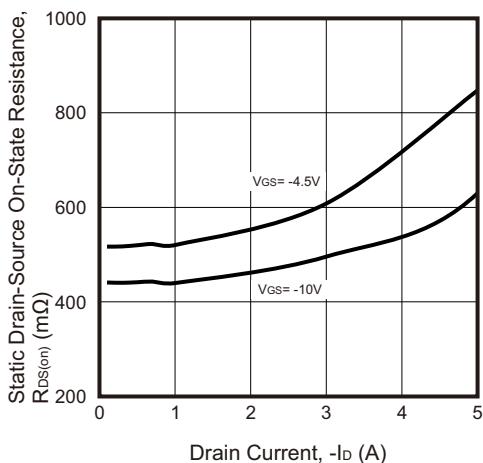


Fig.4 - Body Diode Current vs Source-Drain Voltage

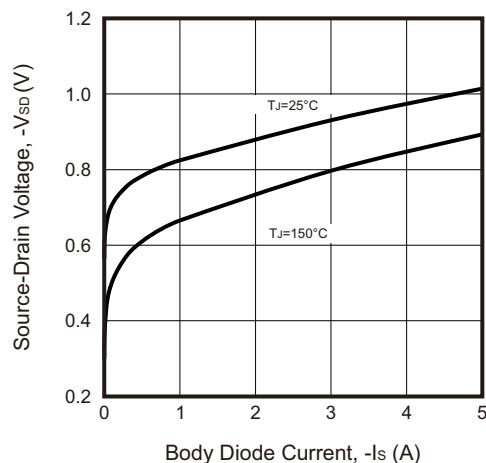


Fig.5 - Static Drain-Source On-State Resistance vs Gate-Source Voltage

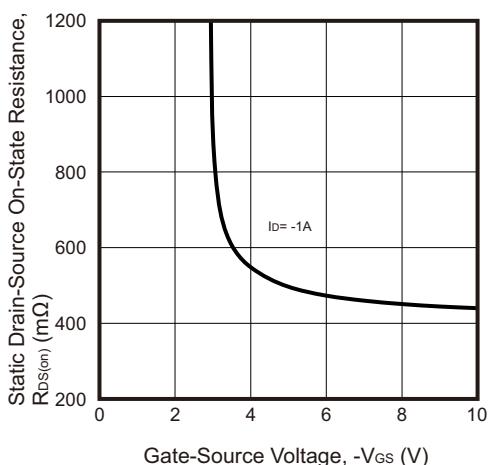
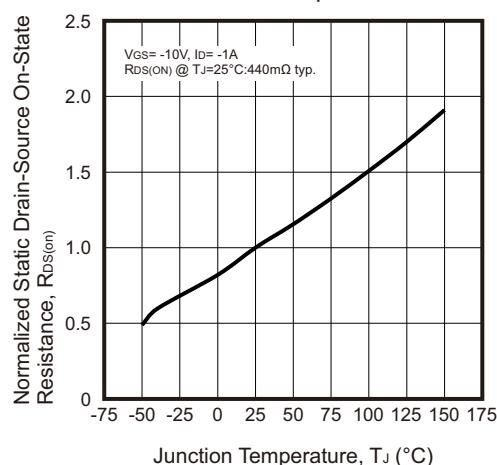


Fig.6 - Drain-Source On-State Resistance vs Junction Temperature



## Rating and Characteristic Curves (CMS01P10TA-HF)

Fig.7 - Capacitance vs Drain-Source Voltage

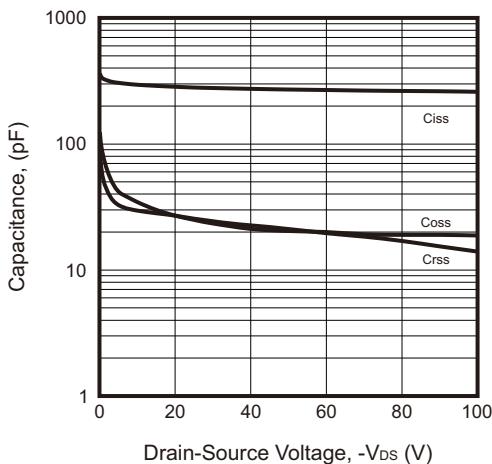


Fig.8 - Threshold Voltage vs Junction Temperature

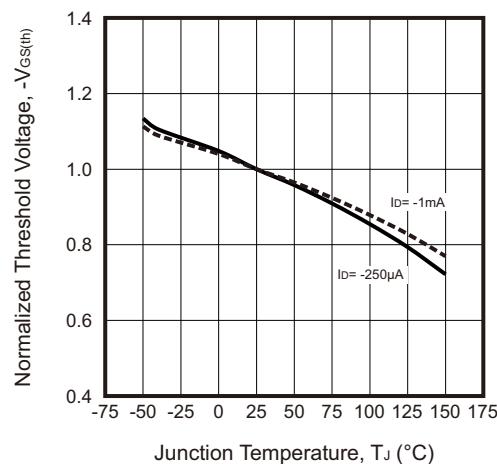


Fig.9 - Forward Transfer Admittance vs Drain Current

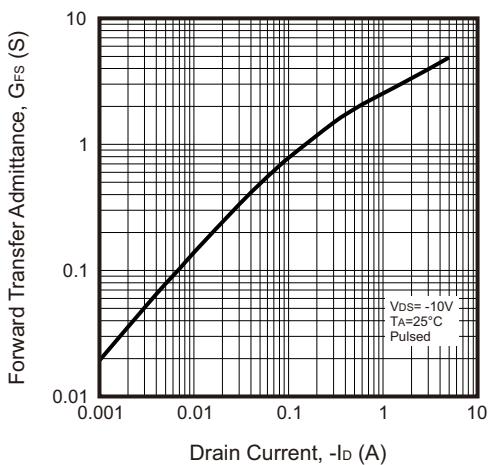


Fig.10 - Gate Charge Characteristics

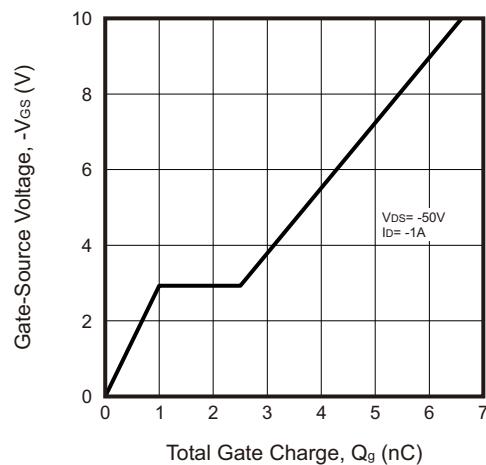


Fig.11 - Maximum Safe Operating Area

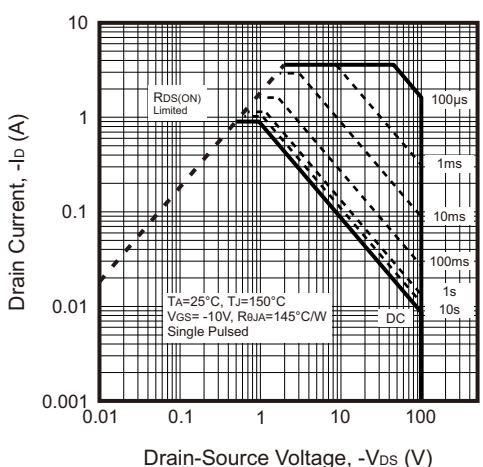
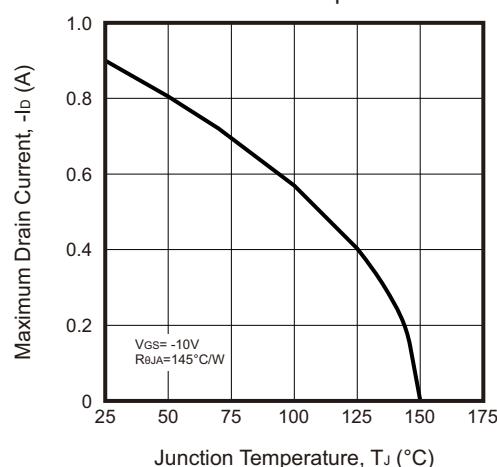
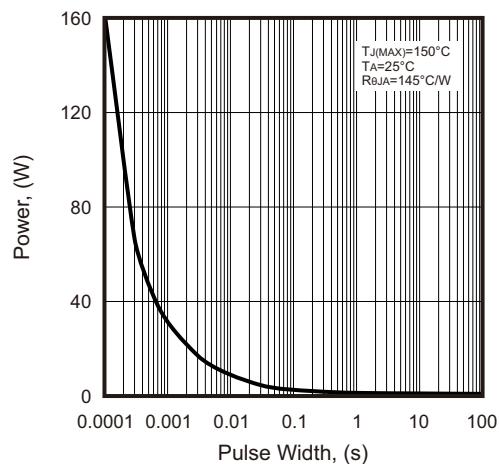


Fig.12 - Maximum Drain Current vs Junction Temperature

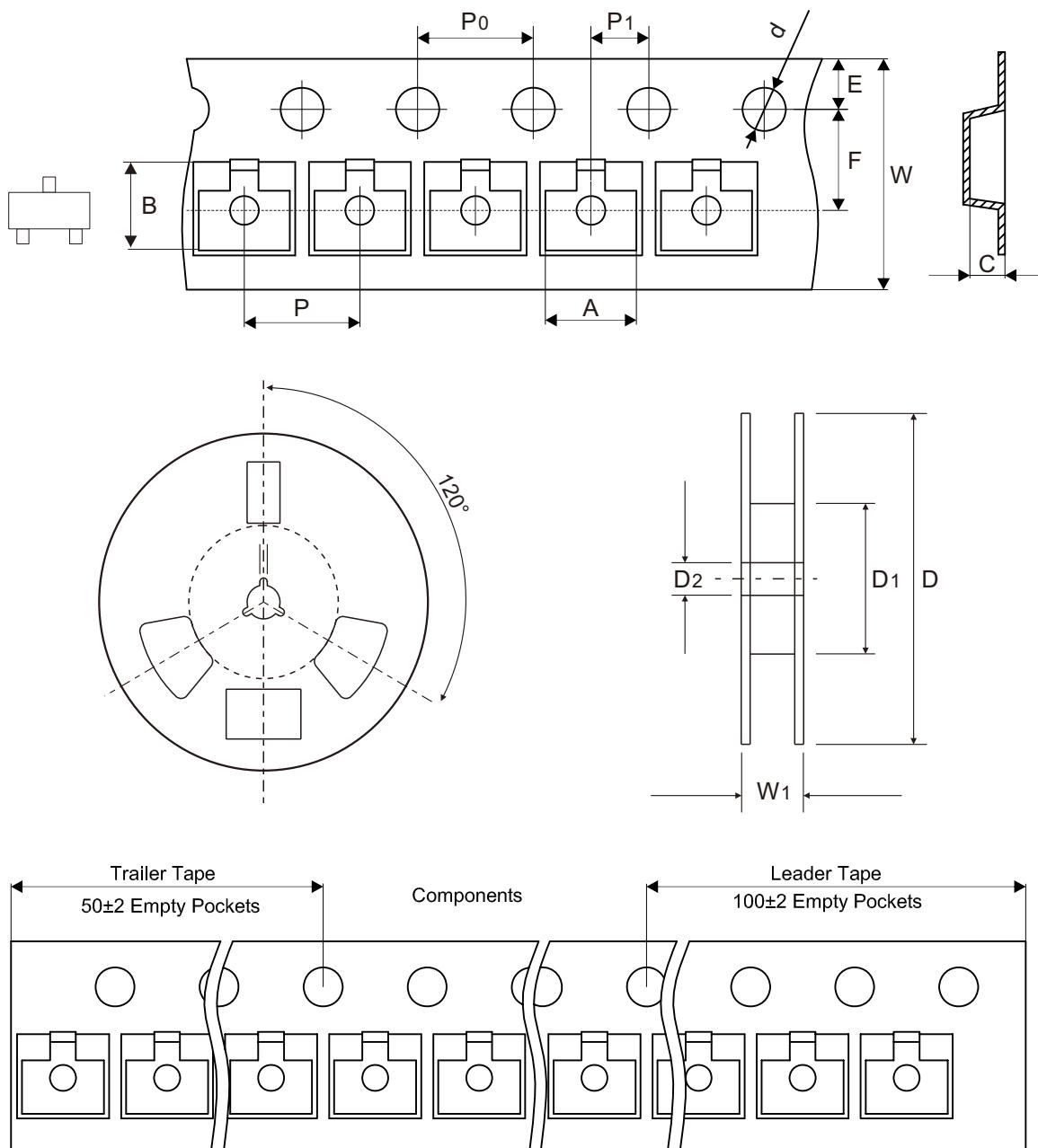


## Rating and Characteristic Curves (CMS01P10TA-HF)

Fig.13 - Single Pulse Power Rating,  
Junction to Ambient



## Reel Taping Specification



SOT-23	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	$3.17 \pm 0.15$	$3.23 \pm 0.12$	$1.37 \pm 0.10$	$1.50 + 0.10$	$179.00 \pm 2.00$	$60.00 \pm 1.50$	$13.50 \pm 0.50$
	(inch)	$0.125 \pm 0.006$	$0.127 \pm 0.005$	$0.054 \pm 0.004$	$0.059 + 0.004$	$7.047 \pm 0.079$	$2.362 \pm 0.059$	$0.531 \pm 0.020$

SOT-23	SYMBOL	E	F	P	P0	P1	W	W1
	(mm)	$1.75 \pm 0.10$	$3.50 \pm 0.05$	$4.00 \pm 0.10$	$4.00 \pm 0.10$	$2.00 \pm 0.05$	$8.00 + 0.30$ $- 0.10$	$16.10 \pm 0.60$
	(inch)	$0.069 \pm 0.004$	$0.138 \pm 0.002$	$0.157 \pm 0.004$	$0.157 \pm 0.004$	$0.079 \pm 0.002$	$0.315 + 0.012$ $- 0.004$	$0.634 \pm 0.024$